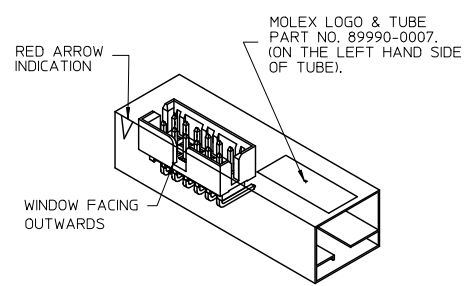
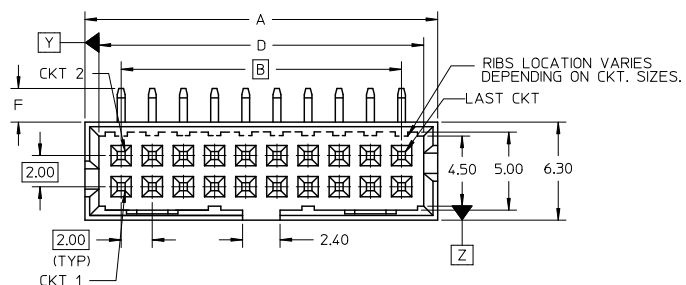
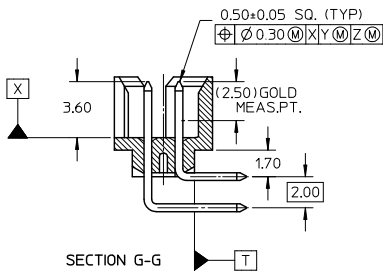
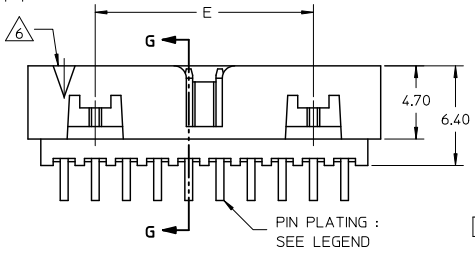


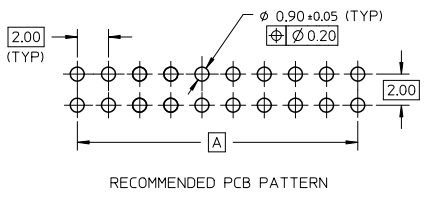
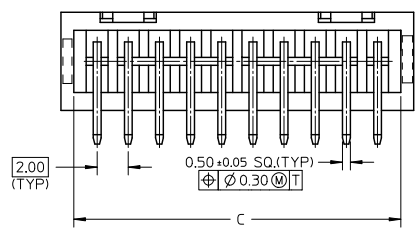
10 9 8 7 6 5 4 3 2 1



REF: ORIENTATION OF PART IN TUBE
(FOR THE REFERENCE OF PART/TUBE ASSEMBLY)



- NOTES:
- FOR ILLUSTRATION PURPOSES, 20 CIRCUIT SIZE WAFER IS SHOWN.
 - MATERIAL :
HOUSING : NYLON 46, UL94V-0, COLOR BLACK.
PIN : 0.50MM SQ.PHOSPHOR BRONZE.
 - PRODUCT SPECIFICATION PS-87831-027 APPLIES.
 - NO CENTRE POLARIZATION SLOT FOR CKT SIZE 4 AND 6.
 - NO SIDE LOCKING SLOT FROM 4 TO 12 CKT SIZE.
 - CKT 4 & 6 HAS NO IDENTIFICATION TAG.
 - THIS HEADER MATES WITH MOLEX:
 - CRIMP RECEPTACLE HOUSING, 51110 SERIES WITH CRIMP TERMINAL, 50394 SERIES.
 - 2MM MILLIGRID DUAL ROW IDT, 87568 SERIES.
 - PARTS TO BE PACKED IN TUBE WITH MOISTURE BARRIER BAG.
 - PLATING SPECIFICATION REFERRED TO SHEET 2.



ADD P/N: 87833-6721 EC NO: S2011-0354 DRWNSKANG 2010/10/18 CHYKATSEE 2010/11/18 APPROVALONG 2010/11/19 BS	QUALITY SYMBOLS 	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION			
		4 PLACES ± --- ± ---	3 PLACES ± --- ± ---	2 PLACES ± 0.2 ± ---	1 PLACE ± --- ± ---	DRAWN BY ATSEE	DATE 2003/10/23	TITLE MGRID, SHROUDED HEADER W/SLOT AND STANDOFF, R/A			
		ANGULAR ± 3°				CHECKED BY KCLING	DATE 2003/11/07	MOLEX MOLEX INCORPORATED			
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				APPROVED BY MLONG	DATE 2010/11/19	MATERIAL NO. SEE TABLE	DOCUMENT NO. SD-87833-010	SHEET NO. 1 OF 3	

9 8 7 6 5 4 3 2 1

10 | 9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1

PART NO.	CKT SIZE	VOID PIN LOCATION	DIMENSION						PLATING OPTION
			A	B	C	D	E	F	
87833-6620	28	-	30.65	26.00	29.00	28.85	22.00	3.18	20
87833-67**	30	-	32.65	28.00	31.00	30.85	24.00		20 OR 21

PART NUMBER LEGEND :
87833 - * * * * *

- PLATING OPTIONS:**
- 18 - 0.38um/15uin PdNi WITH GOLD FLASH IN CONTACT AREA AND 1.88um/75uin MIN.TIN IN SOLDER TAIL AREA OVER 1.27um/50uin MIN. NICKEL OVERALL.
 - 19 - 0.05 - 0.13um/2 - 5uin GOLD IN CONTACT AREA AND 1.88um/75uin MIN.TIN IN SOLDER TAIL AREA OVER 1.27um/50uin MIN. NICKEL OVERALL.
 - 00/ 20 - 0.38um/15uin GOLD IN CONTACT AREA AND 1.88um/75uin MIN.TIN IN SOLDER TAIL AREA OVER 1.27um/50uin MIN. NICKEL OVERALL.
 - 21 - 0.76um/30uin GOLD IN CONTACT AREA AND 1.88um/75uin MIN.TIN IN SOLDER TAIL AREA OVER 1.27um/50uin MIN. NICKEL OVERALL.

ADD P/N: 87833-6721 EC NO: S2011-0354 DRWNSKANG 2010/10/18 CHYKATSEE 2010/11/18 APPROVALONG 2010/11/19	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM ONLY	NTS	METRIC	
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	TITLE		
	▽=0	3 PLACES ± --- ± ---	ATSEE 2003/10/23	MGRID, SHROUDED HEADER W/SLOT AND STANDOFF, R/A		
	▽=0	2 PLACES ± 0.2 ± ---	CHECKED BY DATE	MOLEX INCORPORATED		
	1 PLACE ± --- ± ---	KCLING 2003/11/07	SD-87833-010			
	ANGULAR ± 3°	APPROVED BY DATE	SHEET NO.			
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MLONG 2010/11/19	3 OF 3			
		MATERIAL NO.	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
		SEE TABLE				
		SIZE A3				

tb_frame_A3_P_AM_T
Rev. F 2009/06/18

9 | 8 | 7 | 6 | 5 | 4 | 3 | 2 | 1